

EXHIBIT A

PRELIMINARY DRAFT**LGA - QNL PACKAGE DEVELOPMENT**

<u>Project</u> LGA - QNL PACKAGE DEVELOPMENT	<u>NPEV</u>	<u>Resources</u>
<u>Description</u> Qualify new family of LGA-QNL laminate grid array packages for low to mid-lead count high performance applications. Identify product(s), design & procure substrate, qualify vendors, assemble on MCM-L overmold and saw line, test, conduct failure analysis, and report		
<u>Deliverables</u> Identify lead product and line up support to qualify the package Design and get substrates from qualified suppliers – assemble parts Perform qualification testing, conduct failure analysis and write final report	<u>Forecast</u> 10/98 12/98 4/99	<u>Actual</u>

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